New Prototyping
“Multi Layer Reticle” Service

Multi Layer Reticle (MLR) service enables a reduction in the number of reticles used, which realizes savings in initial development costs, with its flexible tape-out time. This prototyping menu has a great deal of potential for our foundry customers who require several hundred to several thousand engineering samples.

Overview

In addition to the conventional prototyping method using a full set of reticles, FUJITSU SEMICONDUCTOR has been providing “SiExpress,” a shuttle service that reduces prototyping costs and time. FUJITSU SEMICONDUCTOR has now launched the “MLR (Multi Layer Reticle) service,” which is positioned as an intermediate service between conventional prototyping and SiExpress. The MLR method allows the sharing of reticle space between multiple layers of the same design. Since the number of reticles is reduced, the initial engineering costs decrease. Customers need not worry about the tape-out schedule as in SiExpress. We can accept tape-out at any time. We are confident that this prototyping menu will be very useful for our foundry customers who need several hundred to several thousand engineering samples.

Product Features

MLR can have up to four layers of the same specifications built on a single reticle. While reticles and wafers are shared by multiple users in SiExpress, MLR uses both reticles and wafers that are unique to a single user. Therefore, as conventional prototyping, we can accept tape-out at any time and the required number of wafers can be provided. Using the MLR service, prototype products can also be delivered in wafers, whereas products are delivered as chips or packages when using SiExpress.

- **MLR-supported technology**: CS100A_LL (90nm), CS200L (65nm)
- **Wafer size**: 12 inch